

INTERNATIONAL STANDARD

NORME INTERNATIONALE

**Field device integration (FDI) –
Part 103-4: Profiles – PROFINET**

**Intégration des appareils de terrain (FDI) –
Partie 103-4: Profils – PROFINET**



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FIELD DEVICE INTEGRATION (FDI) –

Part 103-4: Profiles – PROFINET

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The text of this standard is based on the following documents:

CDV	Report on voting
65E/355/CDV	65E/418/RVC

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